Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	13	(plasma near (deposit or process)) and (lift with (while or during) with (wafer or substrate) with plasma)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 23:00
L2	33	(plasma near (deposit or process)) and ((de near chuck)or (de-chuck) or (de near clamp)with (before or after) with (wafer or substrate) with plasma)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 23:15
L3	33	(plasma near (deposit or process)) and ((de near chuck)or (de-chuck) or (de near clamp)with (before) with (wafer or substrate) with plasma)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 23:15
L4	33	(plasma near (deposit or process)) and ((de near chuck)or (de-chuck) or (de near clamp)with (wafer or substrate)with (before near\$2 plasma))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 23:22
L5	9	(plasma near (deposit or process)) and (turn near off) with (RF or voltage or power) with (substarte or wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 23:26
L6	35	"478315"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:14
L7	75	((de near chuck) or (de near clamp)) and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:15

L8	75	((de near chuck) or (de near clamp)) and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:15
L9	1	((de near chuck) or (de near clamp)) and (plasma near deposit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:15
L10	33	((de near chuck) or (de near clamp)) and (plasma and deposit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:16
L11	57341	(((de near chuck) or (de near clamp))with before or after) and (plasma and deposit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:16
L12	4	(((de near chuck) or (de near clamp))with (before or after)) and (plasma and deposit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:18
L13	0	((de near chuck) or (de near clamp))with (turn near off)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	OFF	2007/10/27 00:43
L14	1	(plasma with deposit) and ((DC near voltage) with bias with (electrostatic near chuck))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/27 00:47

L15	72	"6316167"	US-PGPUB; USPAT; USOCR; FPRS;	OR	OFF	2007/10/27 00:47
			EPO; JPO; DERWENT; IBM_TDB		,	
S1	0	10/702049	USPAT	OR	OFF	2007/09/17 16:19
S2	2	10/702049	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 12:50
S4	72	"6316167"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:08
S5	7252	((430/313/) or (430/272.1/) or (430/311/) or (427/569/) or (427/282/) or (427/535/)).CCLS.	USPAT; USOCR	OR	OFF	2007/09/18 17:09
S7	3	S5 and TERA	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:11
S8	1666	S5 and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:11
S9	0	S5 and deposit and etch and R:C:H:X	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:12

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S10		S5 and deposit and R:C:H:X	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:12
S11	0	S5 and deposit and R:C:O:X	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:12
S12	2	S5 and R:C:O:X	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:13
S13	2	S5 and RCHX	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:14
S14	37	RCHX	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:14
S15		RCHX and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 17:14
S16	0	RCHX and deposit and HZ	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:09

S17	5	RCHX and deposit	US-PGPUB;	OR	OFF	2007/09/18 17:16
			USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB			
S18	2	"20040178169"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/21 21:18
S19	0	RCHX and HZ and watt	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:09
S20	2	RCHX and HZ	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:10
S21	4	"6903023"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:12
S22	2	"20070037100"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:15
S23	2	"20060049139"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:16

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S24	2	"20040000534"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:26
S25	4	"1905170" ,	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:27
S26	0	"19901905170"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:27
S27	121	"4905170"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/18 19:28
S28	82	"4905170"	USPAT; USOCR	OR	OFF	2007/09/19 12:31
S29	1	2002/0076843	USPAT; USOCR	OR	OFF	2007/09/19 12:32
S30	1	2002/0076843	USPAT; USOCR	OR	OFF	2007/09/19 12:33
S31	6	"6287959"	USPAT; USOCR	OR	OFF	2007/09/19 12:36
S32	20	"6380611"	USPAT; USOCR	OR	OFF	2007/09/19 12:41
S33	439343	(ARC or (anti near reflect\$3 near coat\$4)) deposit and rate and time	USPAT; USOCR	OR	OFF	2007/09/19 12:43
S34	110	(ARC or (anti near reflect\$3 near coat\$4)) with deposit with rate	USPAT; USOCR	OR	OFF	2007/09/19 12:44
S35	1	(anti near reflect\$3 near coat\$4) with deposit with rate	USPAT; USOCR	OR	OFF	2007/09/19 12:47
S36	8249	tetramethylcyclotetrasilicate or tetraethylorthosilicate or dimethyldimetoxysilane or octamethylcyclotetrasiloxane	USPAT; USOCR	OR	OFF	2007/09/19 12:50

S37	13879	tetramethylcyclotetrasilicate or tetraethylorthosilicate or dimethyldimetoxysilane or octamethylcyclotetrasiloxane	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 13:20
S38	1405	S37 and deposit and etch	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 12:52
S39	0	"I0" and (deposit near ratea)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 12:52
S40		"I0" and (deposit near rate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 12:52
S41	. 0	"I0" and (deposit near rate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 12:52
S42	1	"IIO" and (deposit near rate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 12:53
S43	. 95	"IIO" and ((inert near gas) or nitrogen or argon)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 12:54

S44	2	"10662022"	US-PGPUB;	OR	OFF	2007/09/19 13:11
	-		USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB			
S45	4	"7030468"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 13:21
S46	2	"10377061"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 17:09
S47	1	11/023815	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 17:10
S48	1	11/023815	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/19 17:10
S49	4	"7097779"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/21 21:26
S50	0	"SiCOH" with etch with "DC" with bias	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/21 21:27

S51	1	"RCHX" with etch with "DC" with bias	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/24 17:44
S52	1	11/801058	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/09/24 17:45
S53	50	"6316167"	USPAT	OR	OFF	2007/10/03 15:21
S54	50	"6316167"	USPAT	OR	OFF	2007/10/03 15:23
S55	53	etch and SiCH and hydrogen	USPAT	OR	OFF	2007/10/03 15:23
S56	166	etch and SiCH and hydrogen	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/03 15:23
S57	202	etch with SiCH withhydrogen	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/03 15:23
S58	0	etch with SiCH with hydrogen	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/03 15:23
S59	6	etch same SiCH same hydrogen	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/03 15:25

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S60	0	etch same SiCH same hydrogen and	US-PGPUB;	OR	OFF	2007/10/03 15:25
		sccm	USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB			
S61	6	etch same SiCH same hydrogen and rate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/03 15:27
S62	6	"7183201" ·	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/03 15:30
S63	4	09/912103	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/03 15:30
S64	1	"7030008"	USPAT	OR	OFF	2007/10/04 10:24
S65	0	"20050100683"	USPAT	OR	OFF	2007/10/04 10:25
S66	1	"20050100683"	US-PGPUB; USPAT	OR	OFF	2007/10/04 11:09
S67	45	"6063233"	US-PGPUB; USPAT	OR	OFF	2007/10/04 11:34
S68	17	plasma and deposition and SiCOH and shower and temperature	US-PGPUB; USPAT	OR	OFF	2007/10/04 11:35
S69	17	plasma and deposition and SiCOH and shower and temperature	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 11:35
S70	18	plasma and deposit\$4 and SiCOH and shower and temperature	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 11:36

S71	6	plasma and deposit\$4 and SiCOH and (shower with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 11:46
S72	0	(plasma with deposit\$4 with SiCOH)and(post near process)and ((de near chuck) or remove or lift)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 11:47
S73	0	(plasma same deposit\$4 same SiCOH)and(post near process)and ((de near chuck) or remove or lift)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 11:48
S74	4	(plasma and deposit\$4 and SiCOH)and(post near process)and ((de near chuck) or remove or lift)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 12:16
S75	15	plasma and deposit\$4 and (TERA or SiCOH or organosilicate)and(post near process)and((de near chuck) or remove or lift)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 12:26
S76	15	plasma and deposit\$4 and (TERA or SiCOH or SiCNH or organosilicate)and(post near process)and((de near chuck) or remove or lift)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 12:30
S77	7	2002-194431	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 12:35

S78	24	"6380611"	US-PGPUB;	OR	OFF	2007/10/04 12:36
3/6			USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OK	OFF	2007/10/04 12:30
S79	7	"6287959"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 12:39
\$80	2	"20020076843"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 12:45
S81	57	SiCOH and deposit and plasma and (tetramethylylcyclotetrasilane or tetraethylorthosilicate or dimethyldimethoxysilane or octamethylcyclotetrasiloxane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 12:47
S82	24	SiCOHwith deposit with plasma with (tetramethylylcyclotetrasilane or tetraethylorthosilicate or dimethyldimethoxysilane or octamethylcyclotetrasiloxane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 13:06
S83	0	SiCOH with deposit with plasma with (tetramethylylcyclotetrasilane or tetraethylorthosilicate or dimethyldimethoxysilane or octamethylcyclotetrasiloxane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR ·	OFF	2007/10/04 13:06
S84		SiCOH same deposit same plasma same (tetramethylylcyclotetrasilane or tetraethylorthosilicate or dimethyldimethoxysilane or octamethylcyclotetrasiloxane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 13:06

S85	0	SiCOH same deposit same plasma same(tetramethylylcyclotetrasilane or tetraethylorthosilicate or dimethyldimethoxysilane or octamethylcyclotetrasiloxane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF .	2007/10/04 13:06
S86	57	SiCOH and deposit and plasma and(tetramethylylcyclotetrasilane or tetraethylorthosilicate or dimethyldimethoxysilane or octamethylcyclotetrasiloxane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 13:07
S87	75	(SiCOH with deposit\$4) and plasma and(tetramethylylcyclotetrasilane or tetraethylorthosilicate or dimethyldimethoxysilane or octamethylcyclotetrasiloxane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/04 13:22
S88	72	"6316167"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 02:47
S89	3	"20030017694"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 03:08
S90	72	"6316167"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 03:40
S91	33	"6436808"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 03:40

S92	2	deposit and chamber and (SiCOH)and (shower with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 03:46
S93	19466105	US "6764951" B1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 03:44
S94	4	"6764951"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 03:45
S95		(SiCOH)and (shower with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 05:36
S96	5	(SiOH)and (shower with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 03:51
S97	6	organosilicon and (shower with temperature)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 03:52
S98	19	"885985"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 04:26

S99		"20030003768" .	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 04:26
S10 0	2	("SiCOH" or organosilicate)and (shower with temperature)and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 05:37
S10 1	2	("SiCOH" or organosilicate)and (shower with temperature)and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:17
S10 2	16	"638803"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 05:40
S10 3	21	("SiCOH" or organosilicate)and (wall with temperature)and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 05:53
S10 4	9	"938435"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 05:53
S10 5	2	("SiCOH" or organosilicate)and (shower with (temperature or centigrade))and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:24

			1	1	T	
S10 6	16	"638803"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:22
S10 7	331	(shower with (temperature or centigrade))and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:24
S10 8	180	(shower with (temperature or centigrade))and deposit and uniform	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:24
S10 9	3	(shower with (temperature or centigrade))with deposit with uniform	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:28
S11 0	21	(shower with (temperature or centigrade))with deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:43
S11 1	0	((de near chuck\$3) with substrate or wafer)with while with plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:47
S11 2	0	((de near chuck\$3) with substrate or wafer)with while with deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:47

S11 3	0	((de near chuck\$3) with substrate or wafer)same while same deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT;	OR	OFF	2007/10/13 06:47
S11 4	0	((de near chuck\$3) same substrate or wafer)same while same deposit	IBM_TDB US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:47
S11 5	0	(de near chuck\$3) and (substrate or wafer)and while and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:48
S11 6	0	(((de near chuck\$3)with (substrate or wafer)))and while and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 06:53
S11 7	77	(((de near chuck\$3)with (substrate or wafer))) and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 07:00
S11 8	1	(((de adj chuck\$3)with (substrate or wafer))) with deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 07:00
S11 9	1	(((de adj chuck\$3)with (substrate or wafer))) same deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 07:00

S12	1	(((de adj chuck\$3)same (substrate	US-PGPUB;	OR	OFF	2007/10/13 07:00
0		or wafer))) same deposit	USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB			
S12 1	77	(((de adj chuck\$3)same (substrate or wafer))) and deposit	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 07:01
S12 2	76	(((de adj chuck\$3)same (substrate or wafer))) and deposit and (during or while or after or before)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 07:12
S12 3	5440	(((lift\$3)with (substrate or wafer))) and deposit and (during or while or after or before)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 07:12
S12 4	71	(((lift\$3)with (substrate or wafer))) with deposit with (during or while or after or before)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 07:13
S12 5	71	(((lift\$3)with (substrate or wafer))) with deposit with (during or while or after or before)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/13 07:13
S12 6	. 2	"5466524"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/15 18:42

S12 7	1	"10546736"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/15 18:43
S12 8	1	"10546736"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/15 18:44
S12 9	1	10/534401	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/15 18:44
S13 0	64	plasma and (de near chuck)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/24 19:17
S13 1	6	"6452775"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 11:25
S13 2	0	(de near chuk) and (plasma near deposit\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 11:25
S13 3	. 1	(de near chuck) and (plasma near deposit\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 11:28

S13	39	(do noar chuck) and (plasma with	HC-DCDHD.	OP	OFF	2007/10/25 11:20
4		(de near chuck) and (plasma with deposit\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 11:28
S13 5	2	"20050100683"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 11:57
S13 6	. 2	"20050100683"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 11:58
S13 7		((de near chuck or " de-chuck") with (plasma near(coat\$4 or deposit)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 12:00
S13 8	1	((de near chuck or " de-chuck") same (plasma near(coat\$4 or deposit)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 12:00
S13 9	1	((de near chuck or " de-chuck") and (plasma near(coat\$4 or deposit)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 12:00
S14 0	25	((de near chuck or " de-chuck") and (plasma same(coat\$4 or deposit)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 13:40

S14 1	6	"2006004506"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 13:29
S14 2	13	"931272"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 13:29
S14 3	64	(de near chuck or " de-chuck") and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:26
S14 4	2	"20040137169"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:33
S14 5	0	((before with (substrate or wafer)) with lift) and palsma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:34
S14 6		((before same (substrate or wafer)) with lift) and palsma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:34
S14 7	0	((before same (substrate or wafer)) with lift\$4) and palsma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:34

S14 8	0	((before same (substrate or wafer)) same lift\$4) and palsma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:35
S14 9	2940	((before same (substrate or wafer)) same lift\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:35
S15 0	957	((before same (substrate or wafer)) same lift\$4)and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:35
S15 1	2940	((before same (substrate or wafer)) same lift\$4)sameplasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:35
S15 2	223	((before same (substrate or wafer)) same lift\$4)same plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:35
S15 3	34	((before same (substrate or wafer)) same lift\$4)with plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:37
S15 4	21	((before same (substrate or wafer)) with lift\$4)with plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 15:39

S15 5	2	"20060011224"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 15:41
S15 6		"682054"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 15:41
S15 7	21	"623445"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 18:00
S15 8	5753	(plasma antenna with coil)with switch	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 18:44
S15 9	2137	(plasma antenna with coil)with switch and coil	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 18:43
S16 0	205957	(("118") or ("156") or ("343")). CLAS.	USPAT; USOCR	OR	OFF	2007/10/26 18:43
S16 1	11	((plasma and antenna and coil) and switch).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 18:44
S16 2	2	"20030003768"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/26 21:39

S16 3	700	"4951601"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO;	OR	OFF	2007/10/26 22:43
			DERWENT; IBM_TDB			